

30 MAY 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

A / 4 Panel. Andt.
E. Willis
11-13-01

Yoshio YANASE et al.

Attn: BOX PCT

Serial No. NEW

Docket No. 2001-0615A

Filed May 30, 2001

METHOD FOR INSPECTING
SEMICONDUCTOR WAFER SURFACE
[Corresponding to PCT/JP00/07147
Filed October 13, 2000]

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Prior to examination of the above-referenced U.S. patent application please amend the application as follows:

IN THE CLAIMS

Please amend the claims as follows:

A 1

3. (Amended) A method for inspecting a semiconductor wafer surface according to Claim 1, wherein a laser surface inspection apparatus having at least two light optics to one incidence is used as a laser surface inspection apparatus.

4. (Amended) A method for inspecting a semiconductor wafer surface according to Claim 1, wherein the semiconductor wafer is an epitaxial semiconductor wafer.